

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	2327	(134/26,95.2).ccls.	US-PGPUB; USPAT	OR	ON	2008/05/28 15:33
S2	283	(134/23).ccls.	US-PGPUB; USPAT	OR	ON	2008/05/28 15:39
S4	399	(134/33).ccls. and (wafer semiconductor substrate workpiece) and force	US-PGPUB; USPAT	OR	ON	2008/05/28 15:44
S5	80	((kajita same shinji).in. (katakabe same ichiro).in.) and (wafer semiconductor substrate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/28 16:05
S6	455	(156/345.11,345.15).ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/28 16:27
S7	211	S6 and (rotat\$4 centri\$6)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/28 16:28
S8	50	134/87.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/28 16:31
S9	673	438/782.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/28 16:36
S10	20	("6751518" "5944894" "20030236057" "5689749" "5672205" "6247479" "20050000545" "20040219298" "6723151" "6670551" "6911091" "7168224" "20010011640" "20010013161" "20020004100" "6002108" "5454871" "5860181" "6589361" "6309981").pn.	US-PGPUB; USPAT	OR	ON	2008/05/29 09:48

S16	0	"10585482".app.	US-PGPUB; USPAT	OR	ON	2008/05/29 09:54
S17	0	"10/585482".ap.	US-PGPUB; USPAT	OR	ON	2008/05/29 09:54
S18	885	(134/33).ccls.	US-PGPUB; USPAT	OR	ON	2008/05/29 10:17
S19	106	verhaverbeke.in. and (semiconductor wafer substrate)	US-PGPUB; USPAT	OR	ON	2008/05/29 10:56
S20	1	"20020066475".pn.	US-PGPUB; USPAT	OR	ON	2008/05/29 13:51
S21	16116	(rotat\$4 rpm) same (liquid fluid) and (clean\$4 etch\$4) with (wafer semiconductor substrate)	US-PGPUB; USPAT	OR	ON	2008/05/29 17:00
S22	3125	(rpm) same (liquid fluid) and (clean\$4 etch\$4) with (wafer semiconductor substrate)	US-PGPUB; USPAT	OR	ON	2008/05/29 17:01
S23	9472	(rotat\$4 rpm) with (liquid fluid) and (clean\$4 etch\$4) with (wafer semiconductor substrate)	US-PGPUB; USPAT	OR	ON	2008/05/29 17:01
S24	1053	(rpm) with (liquid) and (clean \$4 etch\$4) with (wafer semiconductor substrate)	US-PGPUB; USPAT	OR	ON	2008/05/29 17:02
S25	683	(rpm) with (liquid) and (clean \$4 ) with (wafer semiconductor substrate)	US-PGPUB; USPAT	OR	ON	2008/05/29 17:02
S26	1	"6683007".pn.	US-PGPUB; USPAT	OR	ON	2008/05/29 17:09

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